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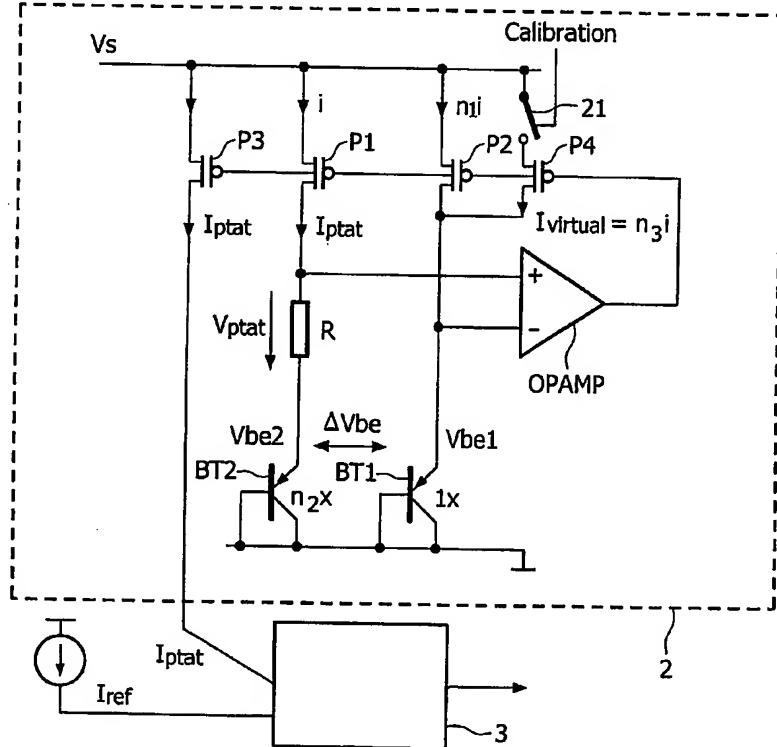
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(54) Title: METHOD AND ARRANGEMENT FOR TEMPERATURE CALIBRATION



(57) Abstract: The invention concerns an arrangement on a semiconductor chip for calibrating temperature setting curve having a signal generation unit (2) for providing a first signal ( $I_{plat1}, V_{plat1}, f_{plat1}$ ), which is proportional to the actual uncalibrated temperature  $T_1$  of the chip. To avoid bringing the chip on a second temperature it is proposed to read a first signal ( $I_{plat1}, V_{plat1}, f_{plat1}$ ), which is proportional to the actual uncalibrated temperature  $T_1$  of the chip and generate a signal offset ( $I_{vir}, V_{vir}, f_{vir}$ ), which is combined with the first signal ( $I_{plat1}, V_{plat1}, f_{plat1}$ ) defining a second signal ( $I_{plat2}, V_{plat2}, f_{plat2}$ ) and to extract a first actual temperature  $T_1$  from the first signal ( $I_{plat1}, V_{plat1}, f_{plat1}$ ) and a second uncalibrated temperature  $T_2$  from the second signal ( $I_{plat2}, V_{plat2}, f_{plat2}$ ).

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